

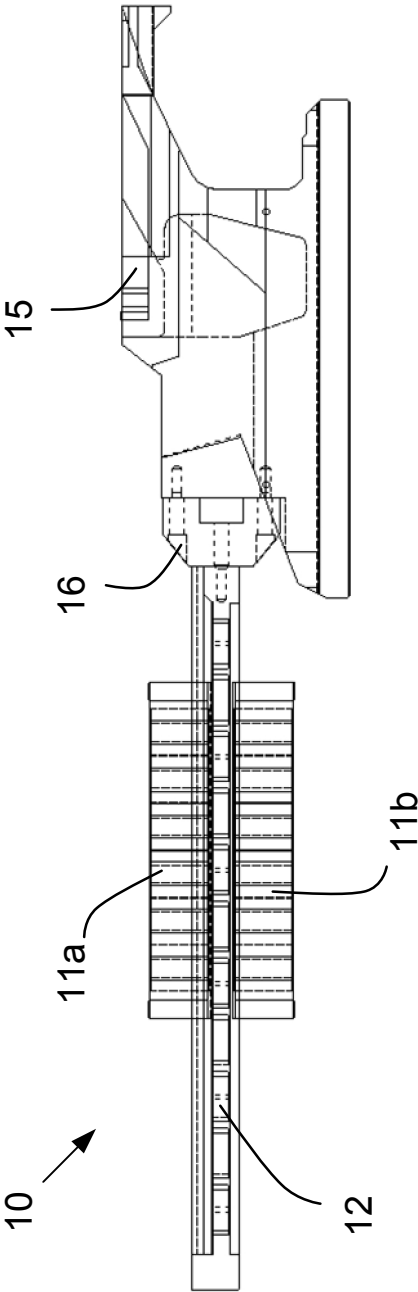


Fig. 1A

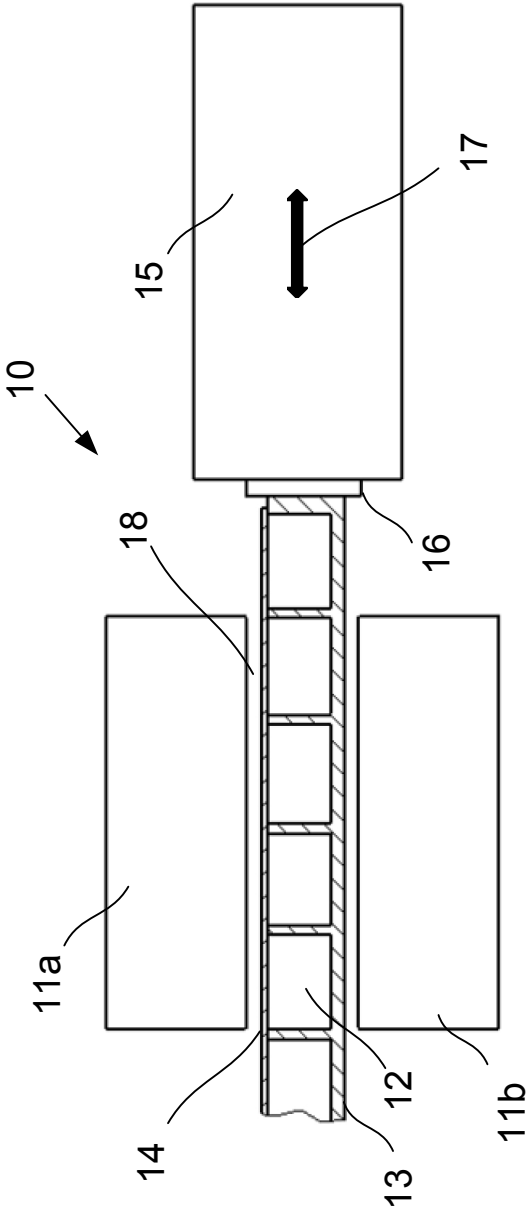


Fig. 1B

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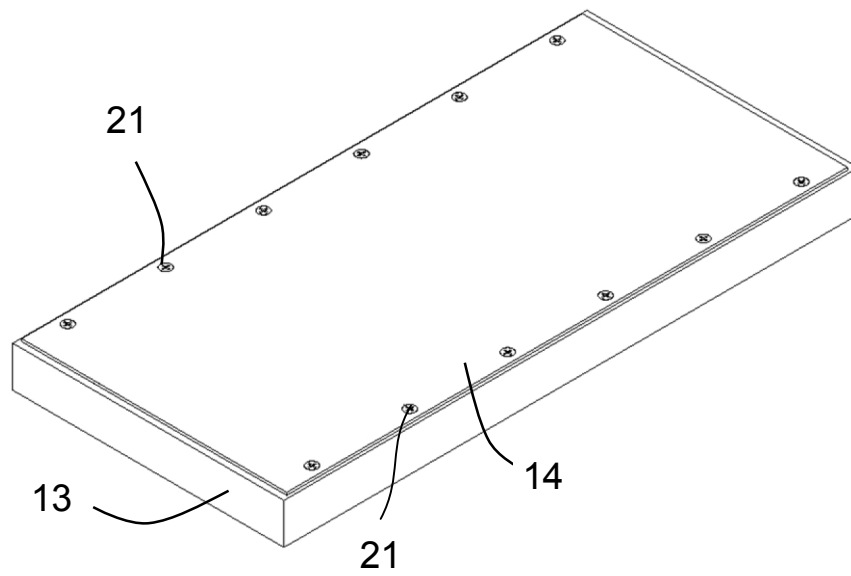


Fig. 2A

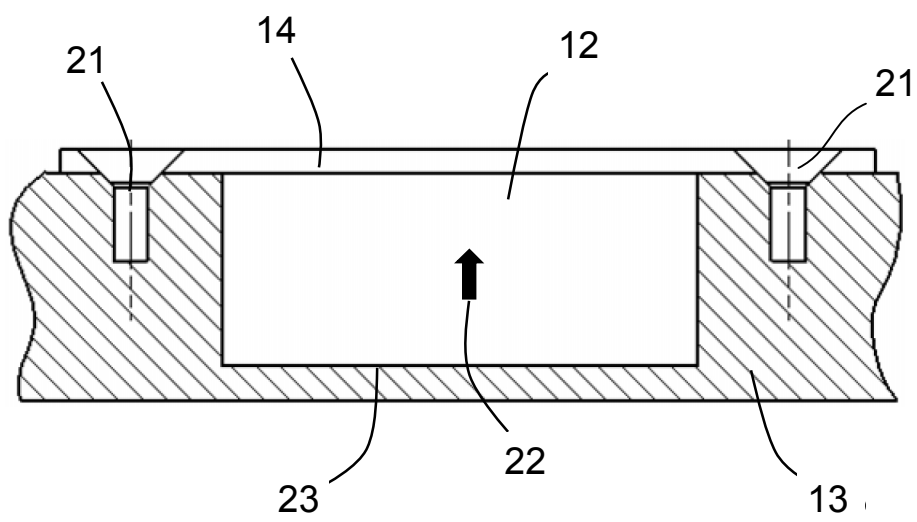


Fig. 2B

A cross-sectional view of a device 110. The device has a central cavity 120. On the left side, there is a component 112a with a vertical pin 140 and a circular feature 130. On the right side, there is a component 111a with a vertical pin 140 and a circular feature 130. The central cavity 120 is bounded by a bottom surface 116 and a top surface 122a. The side components 112a and 111a are mounted on the bottom surface 116. The device 110 is shown in a cross-section with hatching on the outer walls.

A cross-sectional view of a device assembly 310. The assembly includes a central rectangular component 320 with a top surface 321a and a bottom surface 316. This component is mounted on a substrate 310, which is shown with diagonal hatching. Two circular features, likely solder joints or mounting pads, are located on the top surface of the substrate 310, labeled 312a on the left and 311a on the right. Each circular feature contains a smaller circle, labeled 330. The region of the substrate 310 between the two circular features is labeled 322a.

Fig. 5B

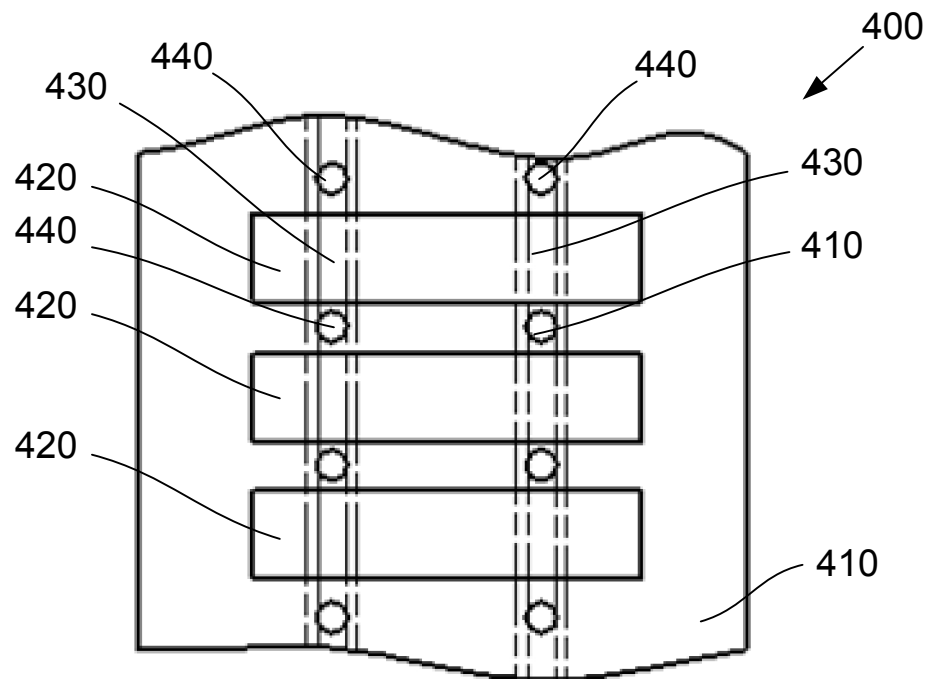


Fig. 6A

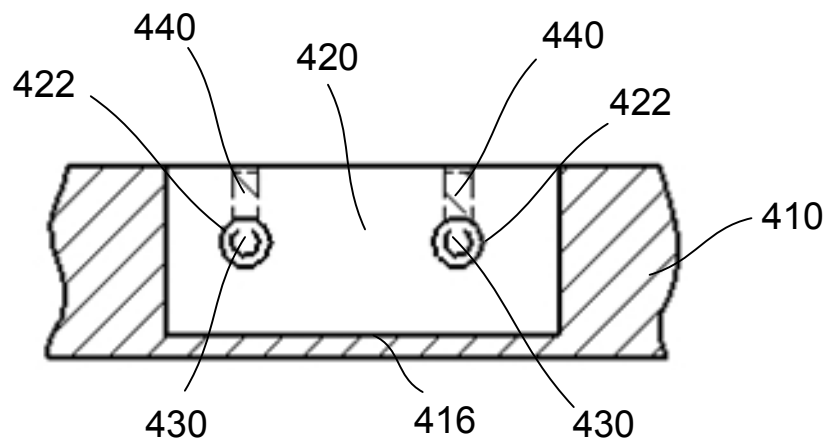


Fig. 6B